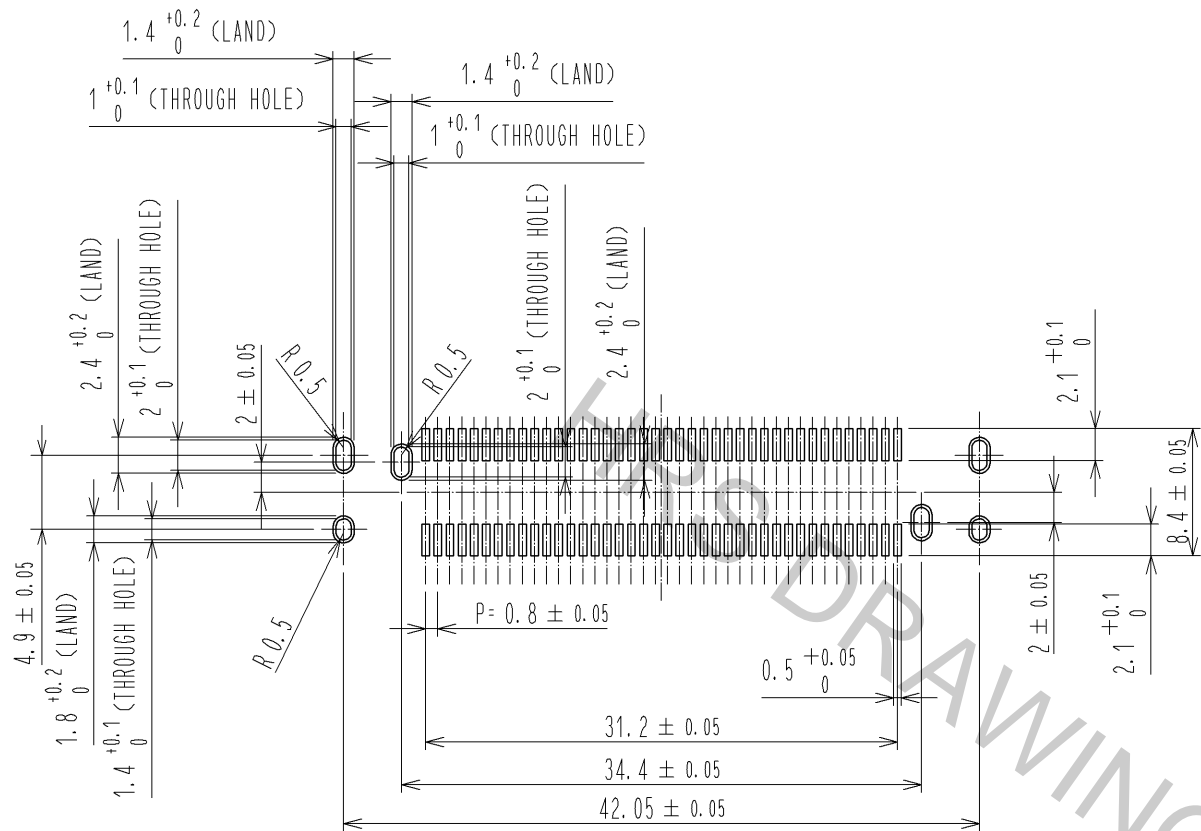


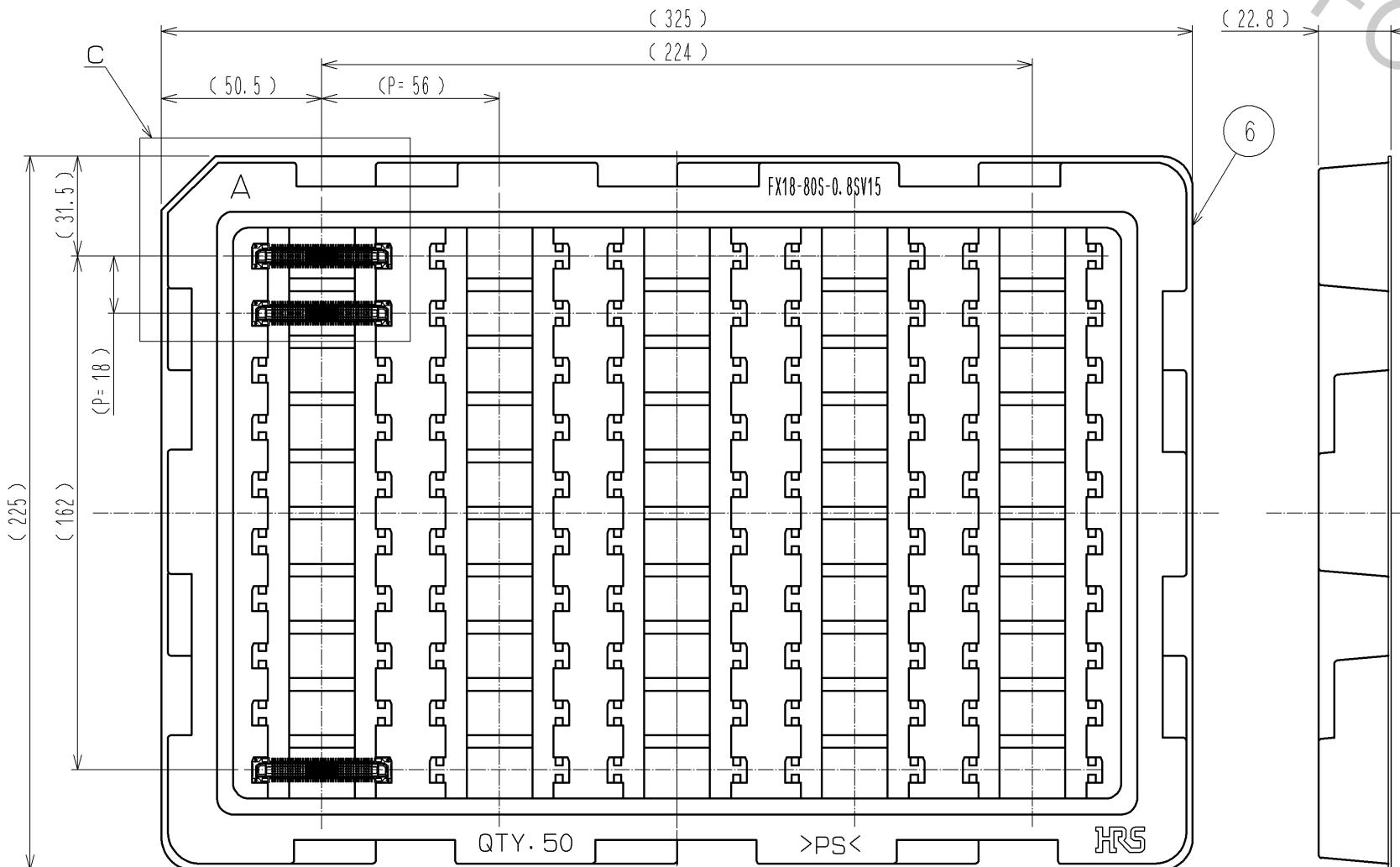
NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.
2 CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A=>SIGNAL CONTACT=>MF CONTACT B)
WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
4 IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2)
REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.
5 THIS IS PACKAGED IN TRAY. (50pcs/TRAY)
6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.
7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm	5	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm
		LEAD AREA:GOLD 0.03 μm			LEAD AREA:TIN-PLATING 1 μm
		UNDER PLATING:NICKEL 1.3 μm			UNDER PLATING:NICKEL 1.3 μm
2	POLYAMIDE	BLACK UL94V-0	4	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm
1	POLYAMIDE	BLACK UL94V-0			LEAD AREA:TIN-PLATING 1 μm
					UNDER PLATING:NICKEL 1.3 μm
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
UNITS mm		SCALE 2 : 1	COUNT		DESCRIPTION OF REVISIONS
HRS		APPROVED : HS. OKAWA	11.08.24		DESIGNED
HIROSE ELECTRIC CO., LTD.		CHECKED : KI. HIROKAWA	11.08.24		CHECKED
		DESIGNED : TH. SANO	11.08.24		DATE
		DRAWN : TH. SANO	11.08.24		
DRAWING NO. EDC3-334388-00				PART NO. FX18-80S-0.8SV15	
CODE NO. CL579-0028-9-00				1/2	

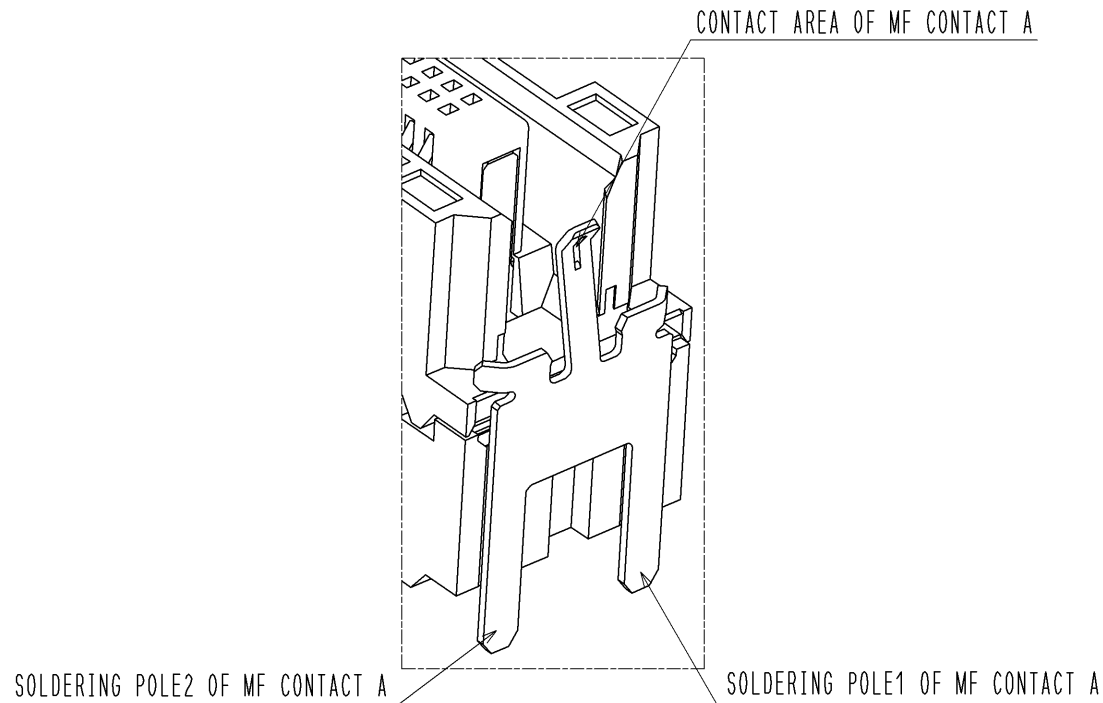
RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)
(PCB THICKNESS:t=1.6mm METAL MASK THICKNESS:t=0.12mm)



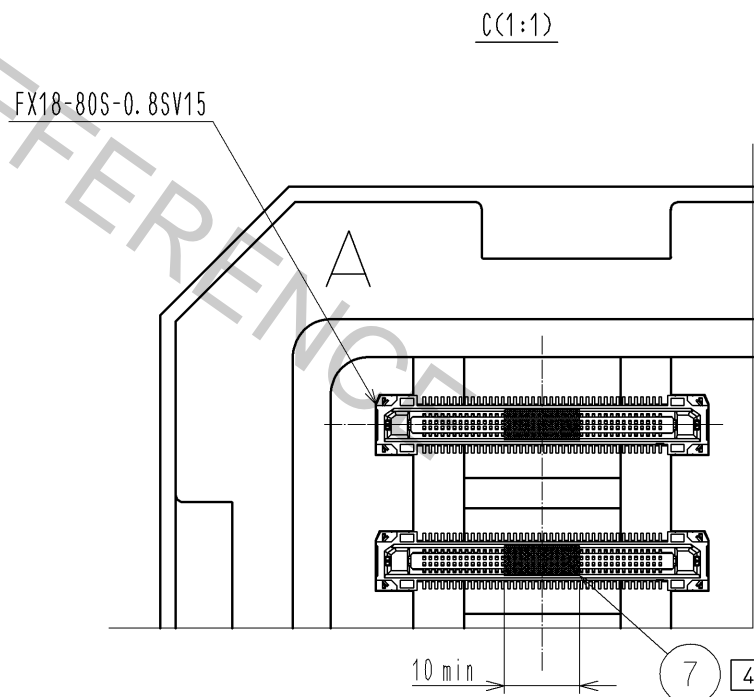
5 DRAWING FOR PACKING(1:2)



8 CONFIGURATION OF MF CONTACT A



NOTE 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES.
BE SURE TO CONNECT TO THE SAME CIRCUIT.



HRS	DRAWING NO.	EDC3-334388-00
	PART NO.	FX18-80S-0.8SV15
	CODE NO.	CL579-0028-9-00
		△ 2/2